



SMD Side View 0802 LED

Part No.: QBLP612-YG

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Introduction

Feature:

- Water clear lens
- Package in tape and reel
- Side View Ultra bright 0802 LED package
- GaP technology for YG

Description:

These ultra bright 0802 LEDs have a height profile of 0.6mm. With higher packing density and smaller footprint, these LEDs are ideal for smaller equipment and miniature application.

Application:

- Status indication
- Back lighting application
- General Use

Certification & Compliance:

- TS16949
- ISO9001
- RoHS Compliant



Dimension:







Units: mm / tolerance = +/-0.1mm

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Electrical / Optical Characteristic (Ta=25 °C)

Product	Color	l _F (mA)	V _F	(V)		λ _D (nm)		l _v (n	ncd)
Froduct Color	1F (111A)	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	
QBLP612-YG	Yellow Green	20	2.0	2.5	565	570	576	5.0	15

Absolute Maximum Rating

Material	P _d (mW)	I _F (mA)	I _{FP} (mA)*	V _R (V)	Т _{оР} (°С)	Т _{ST} (°С)	T _{SOL} (°C)**
GaP	75	30	125	5	-40 ~ +80	-40 ~ +85	260

*Duty 1/8 @ 1kHz

**IR Reflow for no more than 10 sec @ 260 °C

Forward Voltage V_F @ I_F=20mA

Bin	Min.	Max.	Unit
	1.7	2.5	V

Luminous Intensity I_V @ I_F=20mA

Bin	Min.	Max.	Unit
8	5.0	8.0	
9	8.0	12.5	
А	12.5	16	mcd
В	16	20	
С	20	25	

Dominant Wavelength $\lambda_D @ I_F = 20 mA$

Bin	Min.	Max.	Unit
h	565	568	
i	568	572	nm
j	572	576	

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Characteristic Curves



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Solder Profile & Footprint

-Recommended tin solder specifications: melting temperature in the range of 178~192 ^OC -The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):





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Packing

Reel Dimension:



Tape Dimension:



Unit: mm

Arrangement of Tape:



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Packaging Specifications:



Labeling

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Customer P/N:
Item:
Q'ty:
Vf:
WI:
Date:

Made in China

Ordering Information

Part #	Orderable Part #	Spec Range	Quantity per reel
QBLP612-YG	QBLP612-YG	Iv=15mcd typ. @ I _F =20mA, $λ_D$: 565nm ~ 576nm	4,000 units

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Revision History

Description:	Revision #	Revision Date
New Release of QBLP612-YG	V1.0	09/16/2014

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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